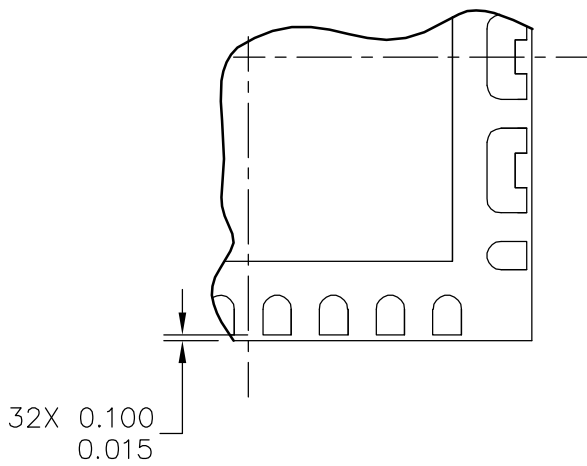
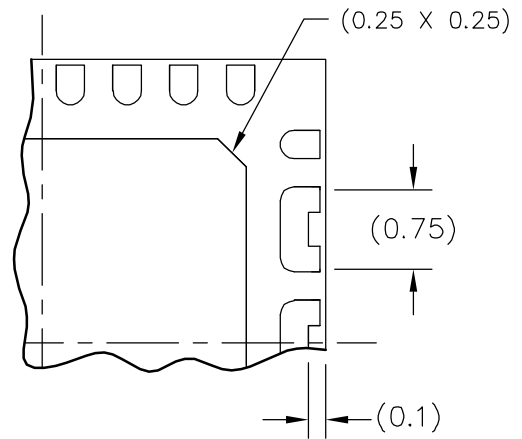


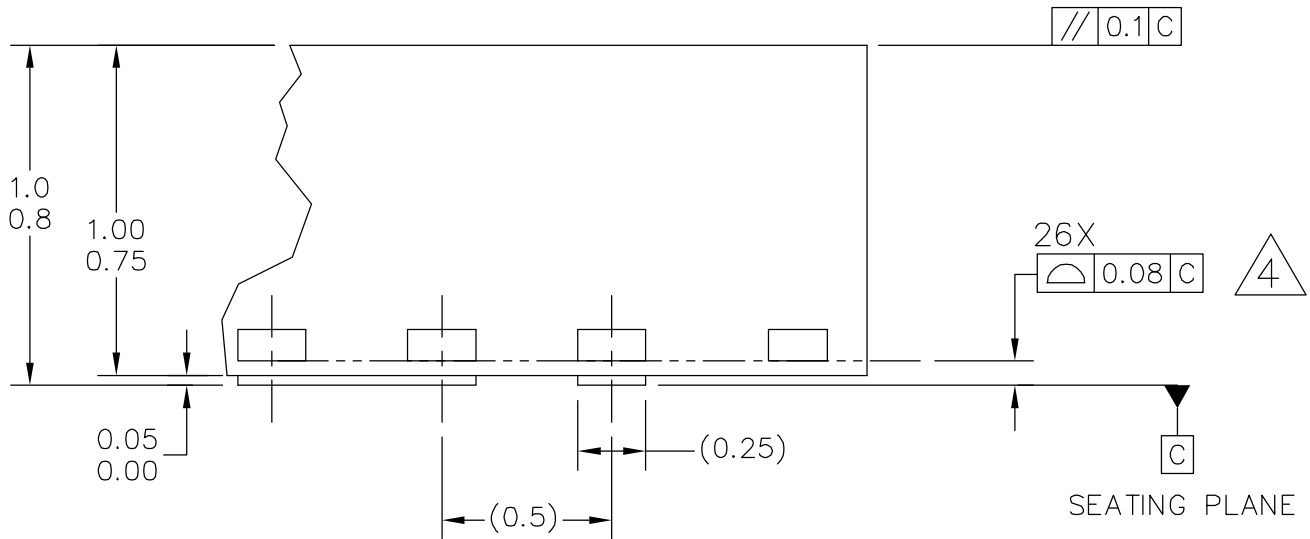
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TITLE: THERMALLY ENHANCED QUAD FLAT NON-LEADED PACKAGE (QFN) 26 TERMINAL, 0.5 PITCH (5 X 5 X 1) 3.6 X 3.6 EP, CASE OUTLINE	DOCUMENT NO: 98ASA10728D	REV: A
	STANDARD: NON-JEDEC	
	SOT1595-2	25 MAR 2016



DETAIL "N"  
CORNER CONFIGURATION



DETAIL "M"  
BACKSIDE PIN 1 INDEX




DETAIL "G"  
VIEW ROTATED 90° CW

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	STANDARD: NON-JEDEC	
	SOT1595-2	25 MAR 2016



NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. THE COMPLETE JEDEC DESIGNATOR FOR THIS PACKAGE IS: HF-PQFN.
4.  COPLANARITY APPLIES TO LEADS, AND DIE ATTACH PAD.
5. MINIMUM METAL GAP SHOULD BE 0.2 MM.

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		SOT1595-2	25 MAR 2016